

# PATENT ASSIGNMENT

Electronic Version v1.1  
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT														
NATURE OF CONVEYANCE:	ASSIGNMENT														
<b>CONVEYING PARTY DATA</b>															
<table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr> <th style="width: 70%;">Name</th> <th style="width: 30%;">Execution Date</th> </tr> </thead> <tbody> <tr> <td>Chih-Chien Liu</td> <td>03/20/2010</td> </tr> <tr> <td>Ta-Shan Tseng</td> <td>03/20/2010</td> </tr> <tr> <td>Wen-Bin Shieh</td> <td>03/20/2010</td> </tr> <tr> <td>Juan-Yuan Wu</td> <td>03/20/2010</td> </tr> <tr> <td>Water Lur</td> <td>03/17/2010</td> </tr> <tr> <td>Shih-Wei Sun</td> <td>03/20/2010</td> </tr> </tbody> </table>		Name	Execution Date	Chih-Chien Liu	03/20/2010	Ta-Shan Tseng	03/20/2010	Wen-Bin Shieh	03/20/2010	Juan-Yuan Wu	03/20/2010	Water Lur	03/17/2010	Shih-Wei Sun	03/20/2010
Name	Execution Date														
Chih-Chien Liu	03/20/2010														
Ta-Shan Tseng	03/20/2010														
Wen-Bin Shieh	03/20/2010														
Juan-Yuan Wu	03/20/2010														
Water Lur	03/17/2010														
Shih-Wei Sun	03/20/2010														
<b>RECEIVING PARTY DATA</b>															
<table border="1" style="width: 100%; border-collapse: collapse;"> <tr> <td style="width: 20%;">Name:</td> <td>UNITED MICROELECTRONICS CORP.</td> </tr> <tr> <td>Street Address:</td> <td>No.3, Li-Hsin Road 2, Science-Based Industrial Park</td> </tr> <tr> <td>City:</td> <td>Hsin-Chu City</td> </tr> <tr> <td>State/Country:</td> <td>TAIWAN</td> </tr> </table>		Name:	UNITED MICROELECTRONICS CORP.	Street Address:	No.3, Li-Hsin Road 2, Science-Based Industrial Park	City:	Hsin-Chu City	State/Country:	TAIWAN						
Name:	UNITED MICROELECTRONICS CORP.														
Street Address:	No.3, Li-Hsin Road 2, Science-Based Industrial Park														
City:	Hsin-Chu City														
State/Country:	TAIWAN														
<b>PROPERTY NUMBERS Total: 1</b>															
<table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr> <th style="width: 30%;">Property Type</th> <th style="width: 70%;">Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>12729234</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	12729234										
Property Type	Number														
Application Number:	12729234														
<b>CORRESPONDENCE DATA</b>															
<p>Fax Number: (703)997-4517</p> <p><i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i></p> <p>Phone: 3027291562</p> <p>Email: Patent.admin.uspto.cr@naipo.com</p> <p>Correspondent Name: WINSTON HSU</p> <p>Address Line 1: P.O.BOX 506</p> <p>Address Line 4: Merrifield, VIRGINIA 22116</p>															
ATTORNEY DOCKET NUMBER:	NAUP1212USA3														
NAME OF SUBMITTER:	SHELLEY KUO														

CH \$40.00 12729234

**501126433**

**PATENT**  
**REEL: 024118 FRAME: 0715**

Total Attachments: 12

source=809687#page1.tif

source=809687#page2.tif

source=809687#page3.tif

source=809687#page4.tif

source=809687#page5.tif

source=809687#page6.tif

source=809687#page7.tif

source=809687#page8.tif

source=809687#page9.tif

source=809687#page10.tif

source=809687#page11.tif

source=809687#page12.tif

**ASSIGNMENT OF INVENTION**

In consideration of the payment by ASSIGNEE to ASSIGNOR of the sum of One Dollar (\$1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration.

**ASSIGNOR(S) (Inventors):**

Name: Chih-Chien Liu Nationality: TW

Name: Ta-Shan Tseng Nationality: TW

Name: Wen-Bin Shieh Nationality: TW

Name: Juan-Yuan Wu Nationality: TW

Name: Water Lur Nationality: TW

Name: Shih-Wei Sun Nationality: TW

Hereby sells, assigns and transfers to

**ASSIGNEE(S):**

Name: UNITED MICROELECTRONICS CORP.

Address: No.3, Li-Hsin Road 2, Science-Based Industrial Park, Hsin-Chu City 300, Taiwan, R.O.C.

and the successors and assignees of the ASSIGNEE the entire right, title, and interest in and to any and all improvements which are disclosed in the invention entitled:

"HIGH DENSITY PLASMA CHEMICAL VAPOR DEPOSITION PROCESS"

Which is found in :

(a) + U.S. patent application executed on even date

(b) \_\_\_\_\_ U.S. patent application executed on \_\_\_\_\_

(c) \_\_\_\_\_ U.S. application serial no. \_\_\_\_\_

(d) \_\_\_\_\_ patent no. \_\_\_\_\_ issued \_\_\_\_\_

## PATENT

and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuations, continuation-in-part, divisions, renewals, substitutes, or extensions thereof, and as to Letters Patent any reissue or re-examination thereof

ASSIGNOR hereby covenants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment;

ASSIGNOR further covenants that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to ASSIGNOR and will testify as to the same in any interference, litigation or proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the proposes thereof.

IN WITNESS WHEREOF, We have hereunto set hand and seal this MAR 20 2010 (Date of signing). (請發明人務必簽署上列日期。)

(Type name of inventor)

Chih-Chien Liu

Ta-Shan Tseng

Wen-Bin Shieh

Juan-Yuan Wu

Water Lur

Shih-Wei Sun

Signature of INVENTOR

Chih-Chien Liu

Ta-Shan Tseng

Juan-Yuan Wu

Water Lur

PATENT

NPO#NAU-P1212-USA:3  
CUST#UMCD-1996-0279-0C1C1C1

*Assignment, Page 4 of 4*

F#NPO-P0002E-US1  
DSC0-099U001417

**PATENT**  
**REEL: 024118 FRAME: 0720**

**ASSIGNMENT OF INVENTION**

In consideration of the payment by ASSIGNEE to ASSIGNOR of the sum of One Dollar (\$1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration.

**ASSIGNOR(S) (Inventors):**

Name: Chih-Chien Liu Nationality: TW

Name: Ta-Shan Tseng Nationality: TW

Name: Wen-Bin Shieh Nationality: TW

Name: Juan-Yuan Wu Nationality: TW

Name: Water Lur Nationality: TW

Name: Shih-Wei Sun Nationality: TW

Hereby sells, assigns and transfers to

**ASSIGNEE(S):**

Name: UNITED MICROELECTRONICS CORP.

Address: No.3, Li-Hsin Road 2, Science-Based Industrial Park, Hsin-Chu City 300, Taiwan, R.O.C.

and the successors and assignees of the ASSIGNEE the entire right, title, and interest in and to any and all improvements which are disclosed in the invention entitled:

"HIGH DENSITY PLASMA CHEMICAL VAPOR DEPOSITION PROCESS"

Which is found in :

(a) + U.S. patent application executed on even date

- (b) \_\_\_\_\_ U.S. patent application executed on \_\_\_\_\_
- (c) \_\_\_\_\_ U.S. application serial no. \_\_\_\_\_
- (d) \_\_\_\_\_ patent no. \_\_\_\_\_ issued \_\_\_\_\_



PATENT

and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuations, continuation-in-part, divisions, renewals, substitutes, or extensions thereof, and as to Letters Patent any reissue or re-examination thereof

ASSIGNOR hereby covenants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment;

ASSIGNOR further covenants that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to ASSIGNOR and will testify as to the same in any interference, litigation or proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the proposes thereof.

IN WITNESS WHEREOF, We have hereunto set hand and seal this MAR 20 2010 (Date of signing). (請發明人務必簽署上列日期。)

(Type name of inventor)

Signature of INVENTOR

Chih-Chien Liu

Ta-Shan Tseng

Wen-Bin Shieh

Juan-Yuan Wu

Water Lur

Shih-Wei Sun

\_\_\_\_\_

\_\_\_\_\_

Wen Bin Shieh

\_\_\_\_\_

\_\_\_\_\_

\_\_\_\_\_

PATENT

NPO#NAU-P1212-USA:3  
CUST#UMCD-1996-0279-0C1C1C1

*Assignment, Page 4 of 4*

F#NPO-P0002E-US1  
DSC0-099U001417

**PATENT**  
**REEL: 024118 FRAME: 0724**

**ASSIGNMENT OF INVENTION**

In consideration of the payment by ASSIGNEE to ASSIGNOR of the sum of One Dollar (\$1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration.

**ASSIGNOR(S) (Inventors):**

Name: Chih-Chien Liu Nationality: TW

Name: Ta-Shan Tseng Nationality: TW

Name: Wen-Bin Shieh Nationality: TW

Name: Juan-Yuan Wu Nationality: TW

Name: Water Lur Nationality: TW

Name: Shih-Wei Sun Nationality: TW

Hereby sells, assigns and transfers to

**ASSIGNEE(S):**

Name: UNITED MICROELECTRONICS CORP.

Address: No.3, Li-Hsin Road 2, Science-Based Industrial Park, Hsin-Chu City 300, Taiwan, R.O.C.

and the successors and assignees of the ASSIGNEE the entire right, title, and interest in and to any and all improvements which are disclosed in the invention entitled:

**"HIGH DENSITY PLASMA CHEMICAL VAPOR DEPOSITION PROCESS"**

Which is found in :

(a) + U.S. patent application executed on even date

- (b) \_\_\_\_\_ U.S. patent application executed on \_\_\_\_\_
- (c) \_\_\_\_\_ U.S. application serial no. \_\_\_\_\_
- (d) \_\_\_\_\_ patent no. \_\_\_\_\_ issued \_\_\_\_\_

PATENT

and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuations, continuation-in-part, divisions, renewals, substitutes, or extensions thereof, and as to Letters Patent any reissue or re-examination thereof

ASSIGNOR hereby covenants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment;

ASSIGNOR further covenants that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to ASSIGNOR and will testify as to the same in any interference, litigation or proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the proposes thereof.

IN WITNESS WHEREOF, We have hereunto set hand and seal this MAR 20 2010 (Date of signing). (請發明人務必簽署上列日期。)

(Type name of inventor)

Signature of INVENTOR

Chih-Chien Liu

\_\_\_\_\_

Ta-Shan Tseng

\_\_\_\_\_

Wen-Bin Shieh

\_\_\_\_\_

Juan-Yuan Wu

\_\_\_\_\_

Water Lur

Water Lur Mar. 17, 2010

Shih-Wei Sun

\_\_\_\_\_

PATENT

NPO#NAU-P1212-USA:3  
CUST#UMCD-1996-0279-0C1C1C1

*Assignment, Page 4 of 4*

F#NPO-P0002E-US1  
DSC0-099U001417

**RECORDED: 03/23/2010**

**PATENT**  
**REEL: 024118 FRAME: 0728**